



DEVICE MIGRATION
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ISSUE DATE: 22-Apr-2016
NOTIFICATION: 17148
TITLE: MCZ33812 Device Migration with Copper Wire and Stamped Leadframe
LAST BUY DATE: 12-Oct-2016
LAST SHIP DATE: 15-Apr-2017

DEVICE(S)

MPN	REPLACEMENT MPN	REPLACEMENT TYPE	REPLACEMENT REASON
MCZ33812AEK	MCZ33812AEK Replaced BY MC33812EK	Same Fit & Function, Different Form, Pin-for-Pin Equivalent	Bill of Material Change (same assembly site)
MCZ33812AEKR2	MCZ33812AEKR2 Replaced BY MC33812EKR2	Same Fit & Function, Different Form, Pin-for-Pin Equivalent	Bill of Material Change (same assembly site)
MCZ33812EK	MCZ33812EK Replaced BY MC33812EK	Same Fit & Function, Different Form, Pin-for-Pin Equivalent	Bill of Material Change (same assembly site)
MCZ33812EKR2	MCZ33812EKR2 Replaced BY MC33812EKR2	Same Fit & Function, Different Form, Pin-for-Pin Equivalent	Bill of Material Change (same assembly site)

DESCRIPTION OF CHANGE

NXP Semiconductors announces the Device Migration of MCZ33812EK/R2 and MCZ33812AEK/R2 to MC33812EK/R2, along with Copper (Cu) Wire as a wirebond material, Sumitomo EME-G630AY mold compound, and stamped leadframe. These products are now qualified for assembly at NXP ATTJ assembly site, Tianjin China. These products were previously assembled with Gold (Au) wire, Hitachi CEL9220HF13 mold compound and etched leadframe at NXP ATTJ assembly site, Tianjin China. The leadframe change is required to standardize and align with current ATTJ production SOIC stamped leadframe designs. The leadframe materials and vendor are identical to previous. However, the form of the exposed pad area changed slightly, but is still within case outline limits. See details in attached leadframe conversion summary.

The new parts are backward compatible to the original parts. Customers should begin planning for conversion based on the last order date and last ship date listed above.

Samples available for MC33812EK/R2.

REASON FOR CHANGE

Part consolidation with the transfer from Gold to Copper wire, CEL9220HF13 to EME-G630AY mold compound and etched to stamped leadframe required to mitigate against raw material cost increases and for supply assurance.

ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)

Replacement parts have slight change to form at leadframe exposed pad area, but still within case outline. No Impact to fit or function. Reliability is equivalent or improved.

NXP will consider specific conditions of acceptance of this change submitted within 30 days of receipt of this notice on a case by case basis. To request further data or inquire about the notification, please enter a [Support Case](#). **Be aware that after you select this link to enter your request, you must choose the topic "Product Change Notification" once on the Salesforce page.**

For sample inquiries - please go to www.nxp.com

QUAL DATA AVAILABILITY DATE: 20-May-2015

QUALIFICATION STATUS: COMPLETED

QUALIFICATION PLAN:

N/A

RELIABILITY DATA SUMMARY:

N/A

ELECTRICAL CHARACTERISTIC SUMMARY:

N/A

CHANGED PART IDENTIFICATION:

N/A

SAMPLE AVAILABILITY DATE: 12-Jun-2015

ATTACHMENT(S):

External attachment(s) FOR this notification can be viewed AT:

[17148 MCZ33812 Copper Wire and Stamped LF Qualification Results.pdf](#)

[17148 MCZ33812 Copper Wire and Stamped LF Electrical Distribution.pdf](#)

[17148 MCZ33812 Copper Wire and Stamped LF C of DC Comparison.pdf](#)

[17148 MCZ33812 Copper Wire and Stamped LF Delta-Qualification-Matrix-ZVEI.pdf](#)

[17148 SOIC32 Leadframe Conversion Summary.pdf](#)
